

Welcome to EJ2300 Power Electronics

Basics

DC/DC converters

DC-motor

Diode and thyristor converters

Power semiconductors (web-based)

Inverters

Switching DC power supplies

Power Electronic Systems

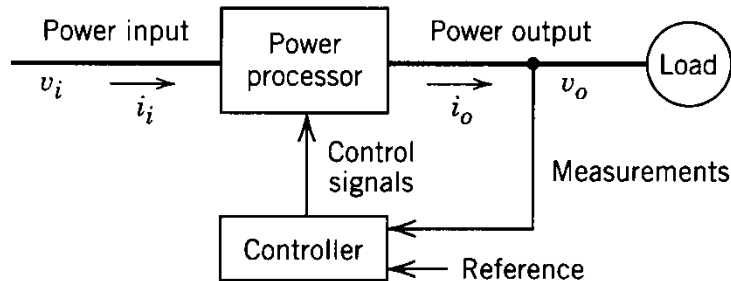
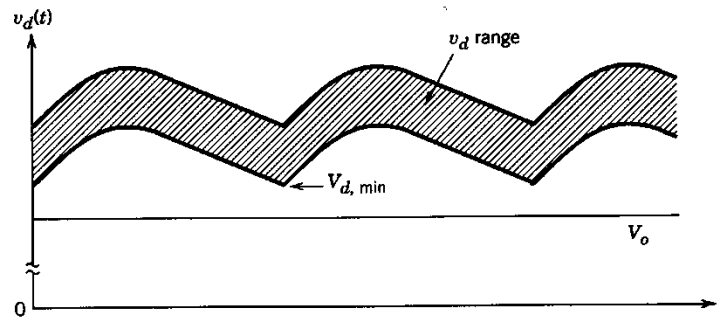
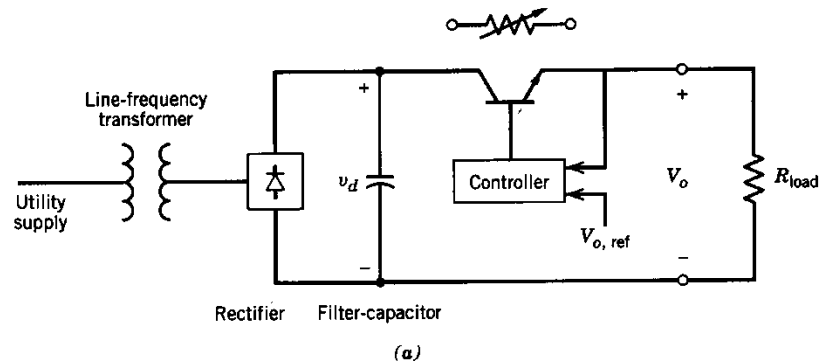


Figure 1-1 Block diagram of a power electronic system.

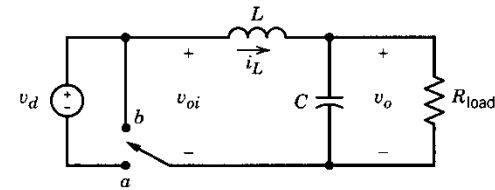
- Block diagram
- Role of Power Electronics
- Reasons for growth (power semiconductors, digital electronics, renewables, electric vehicles)

Linear Power Supply

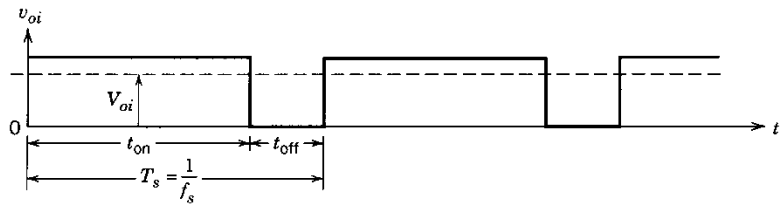


- Series transistor as an adjustable resistor
- Low Efficiency
- Heavy and bulky

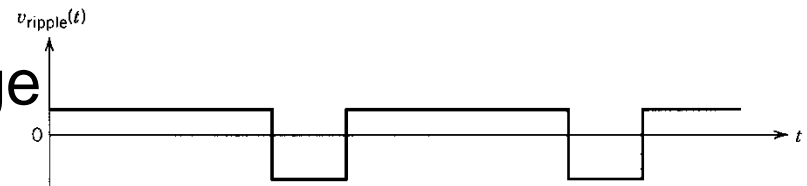
Basic Principle of Switch-Mode Synthesis



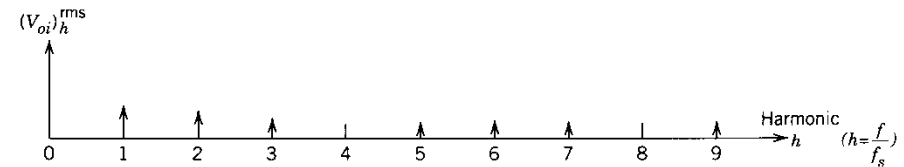
(a)



(b)



(c)

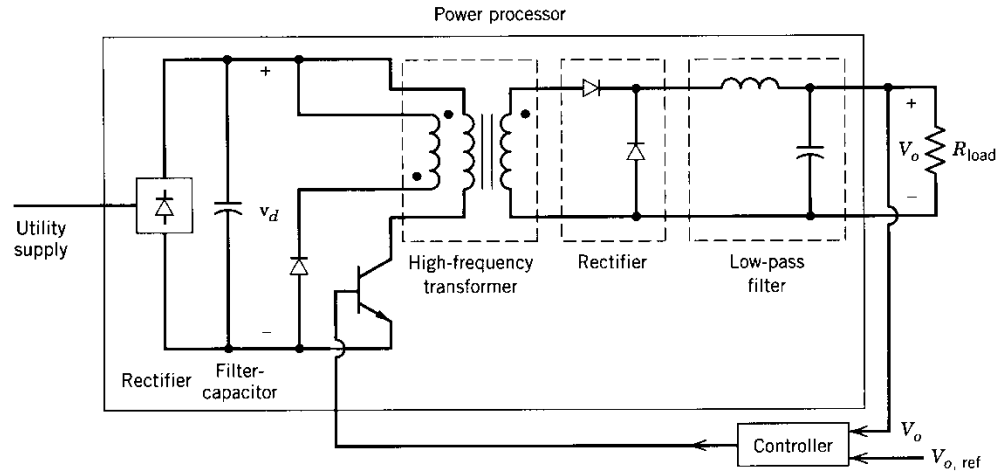


(d)

- Constant switching frequency
- pulse width controls the average
- L-C filters the ripple

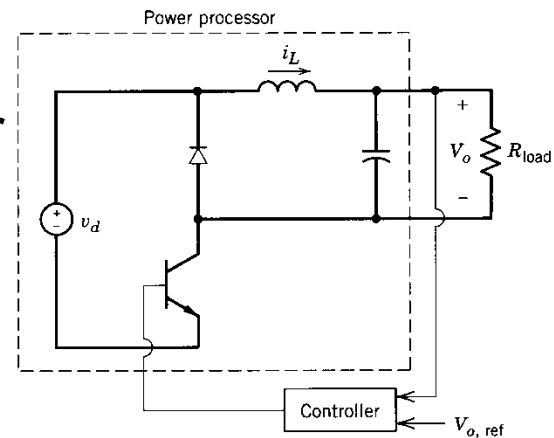
Figure 1-4 Equivalent circuit, waveforms, and frequency spectrum of the supply in Fig. 1-3.

Switch-Mode Power Supply



(a)

- Transistor as a switch
- High Efficiency
- High-Frequency Transformer



(b)

Figure 1-3 Switch-mode dc power supply.

AC Motor Drive

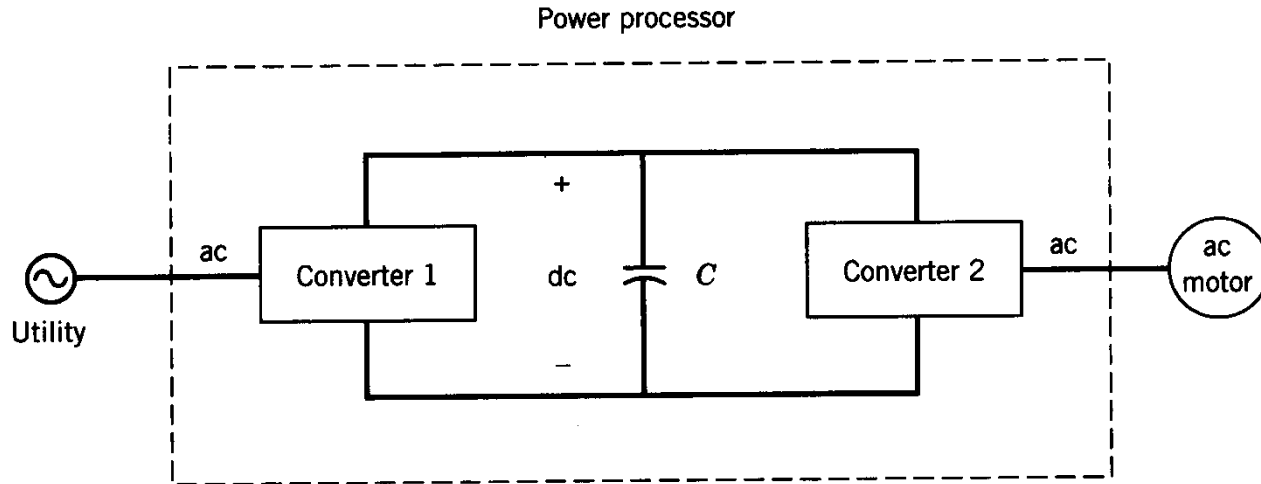


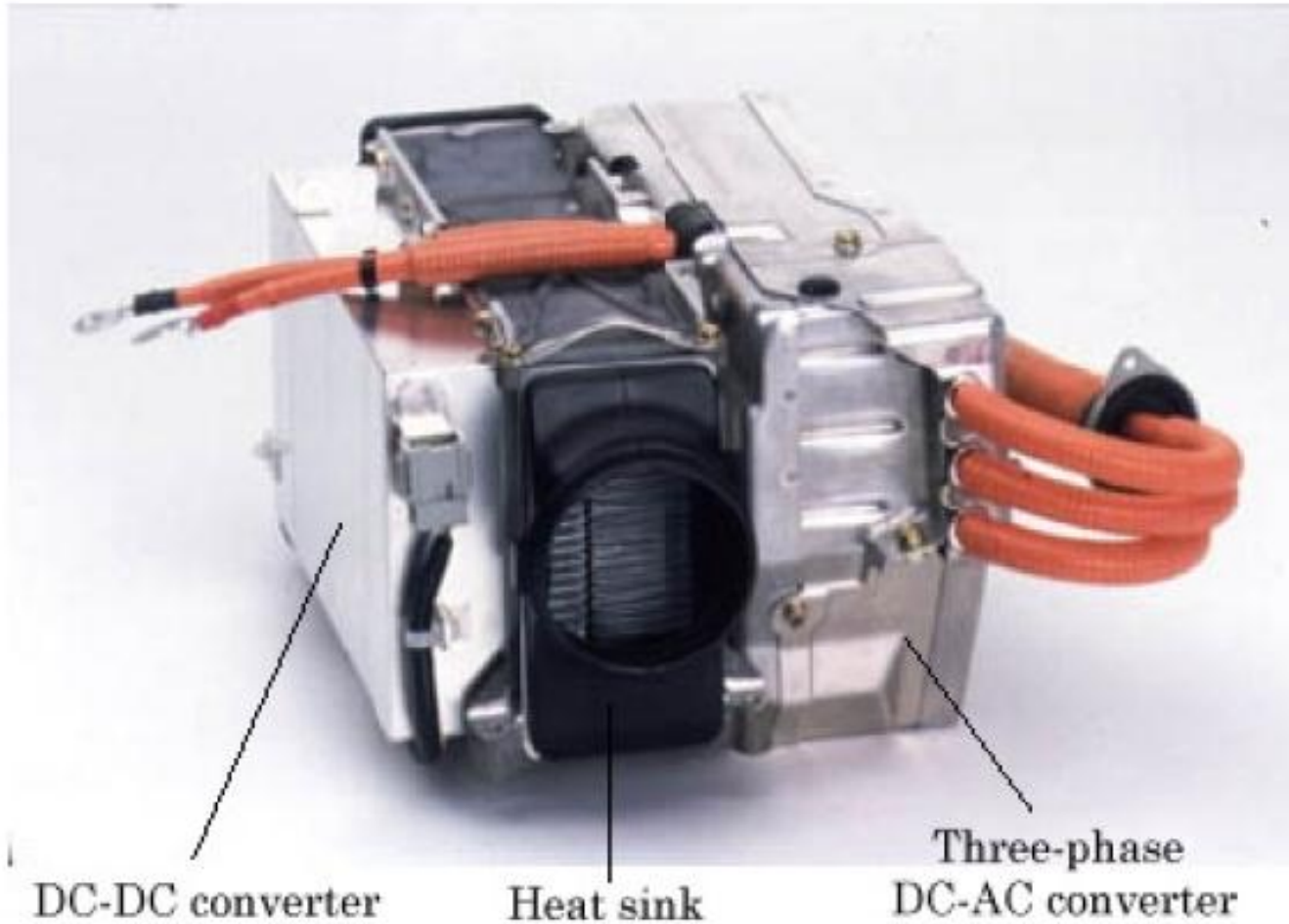
Figure 1-8 Block diagram of an ac motor drive.

- Converter 1 rectifies line-frequency ac into dc
- Capacitor acts as a filter; stores energy; decouples
- Converter 2 synthesizes low-frequency ac to motor
- Polarity of dc-bus voltage remains unchanged
 - ideally suited for transistors of converter 2

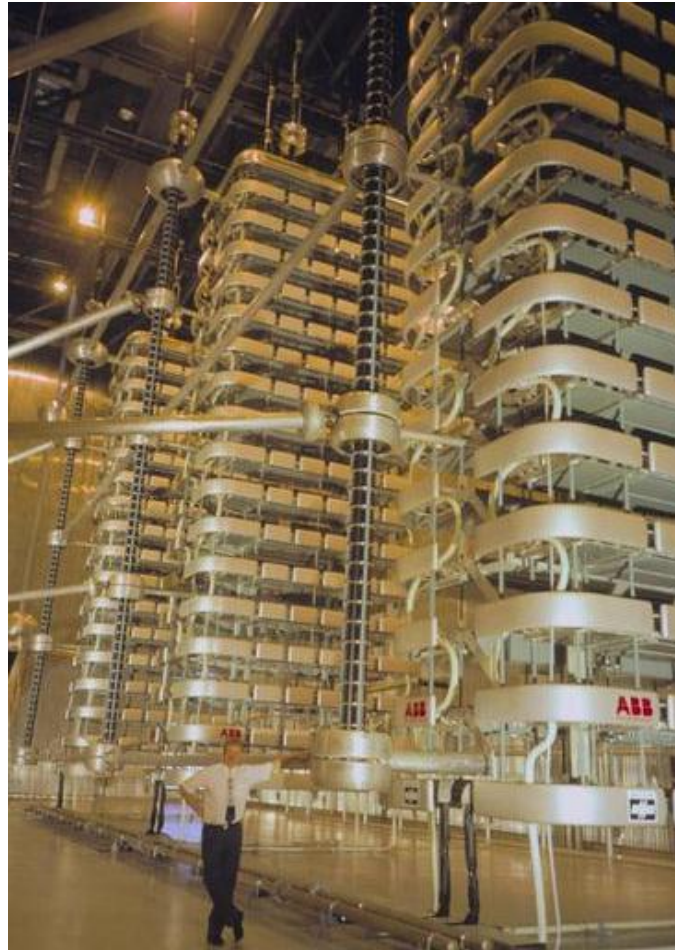
Applications

- Controlled DC power supplies
- Motor drives for various applications (industry, transport)
- Grid applications (HVDC, SVC, StatCom, TCSC)
- Windpower
- Photovoltaics

Honda Insight



Thyristor valve for HVDC 500 kV, 1500 MW



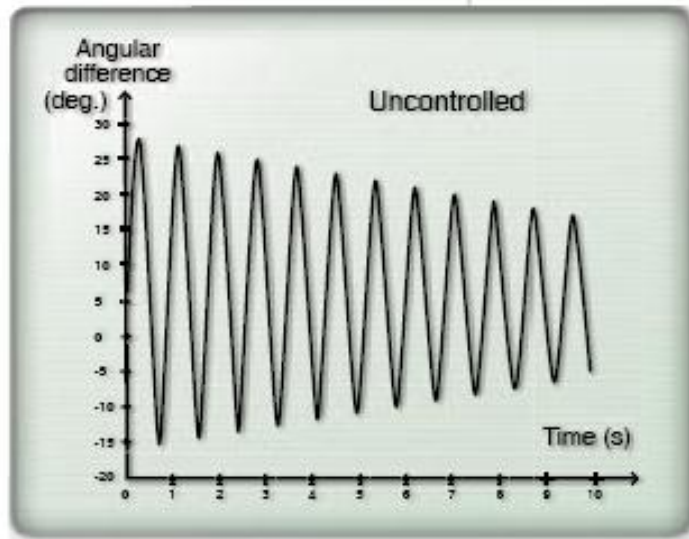
Source: ABB

Thyristor Controlled Series Compensator 400 kV, 394 Mvar fixed, 71 Mvar controlled

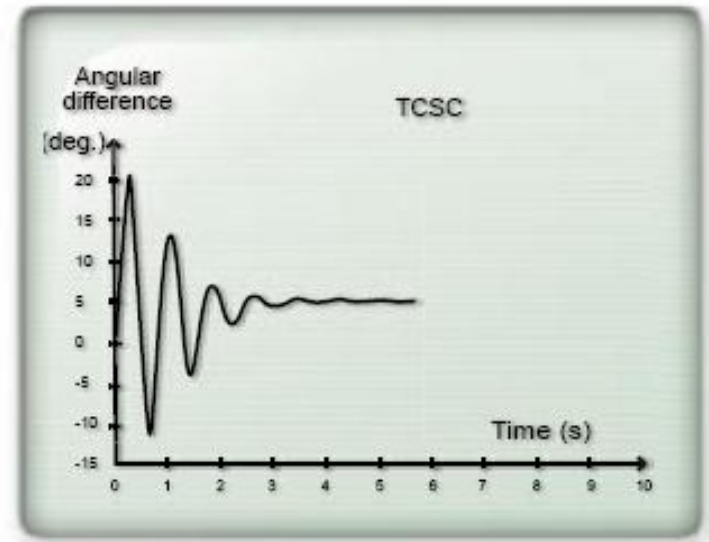


Power oscillation damping with TCSC

500 kV, 2000 MW line

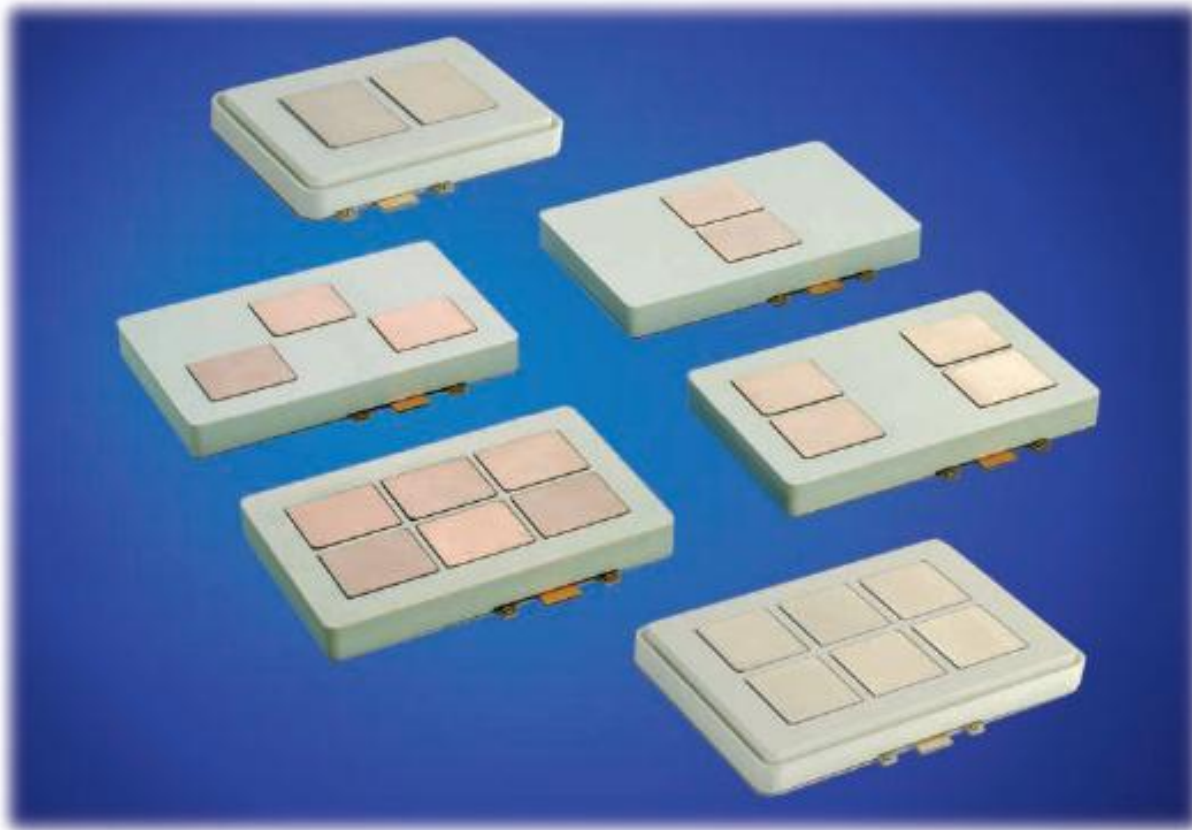


a)



b)

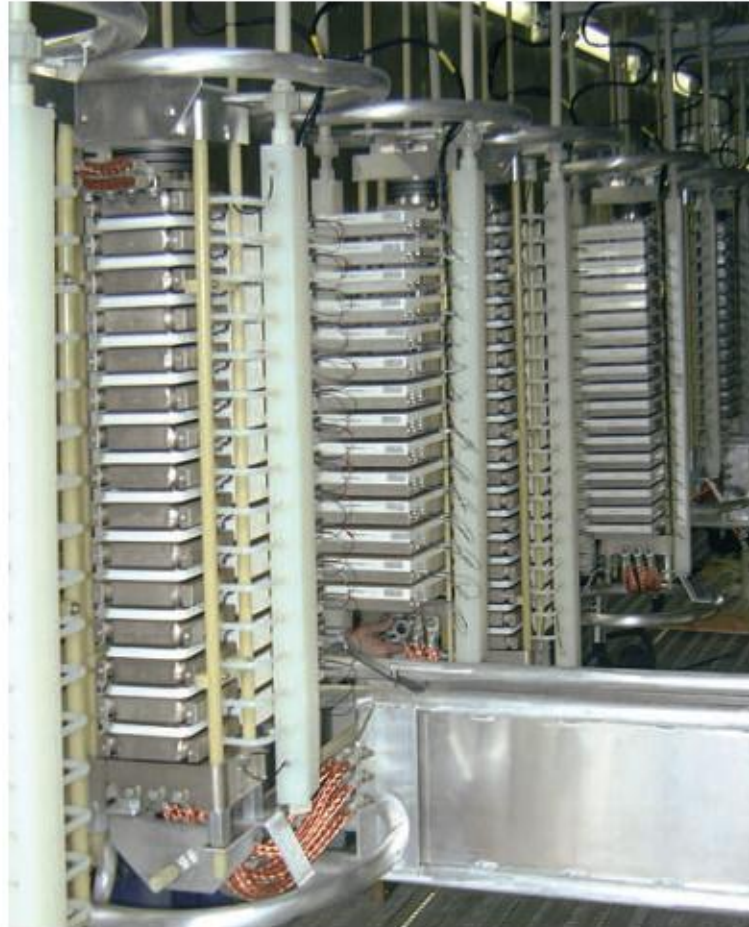
IGBT press-pack modules



IGBT stacks



Valve assembly



Cooling system



Source: ABB

High-voltage PEX cable



Electrostatic precipitator

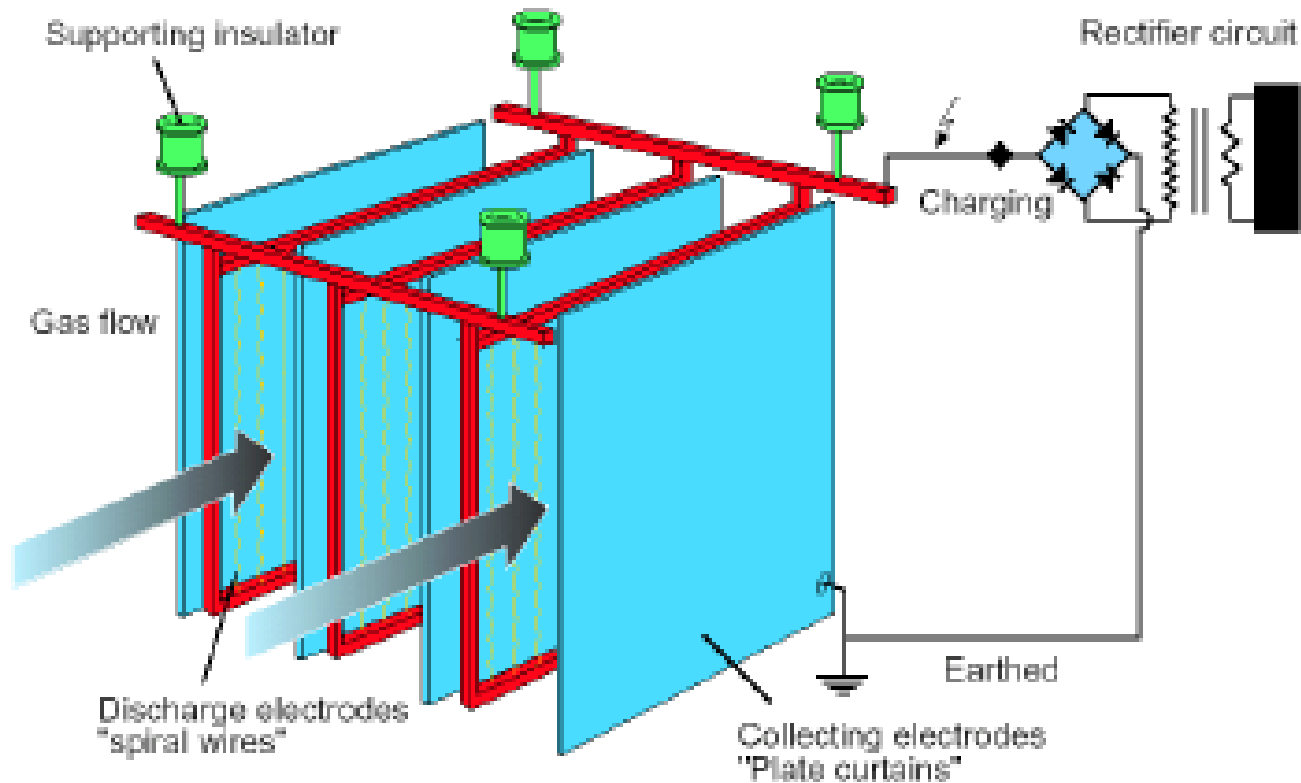


Figure 2.3 Typical design of bus-section of an ESP

Diodes

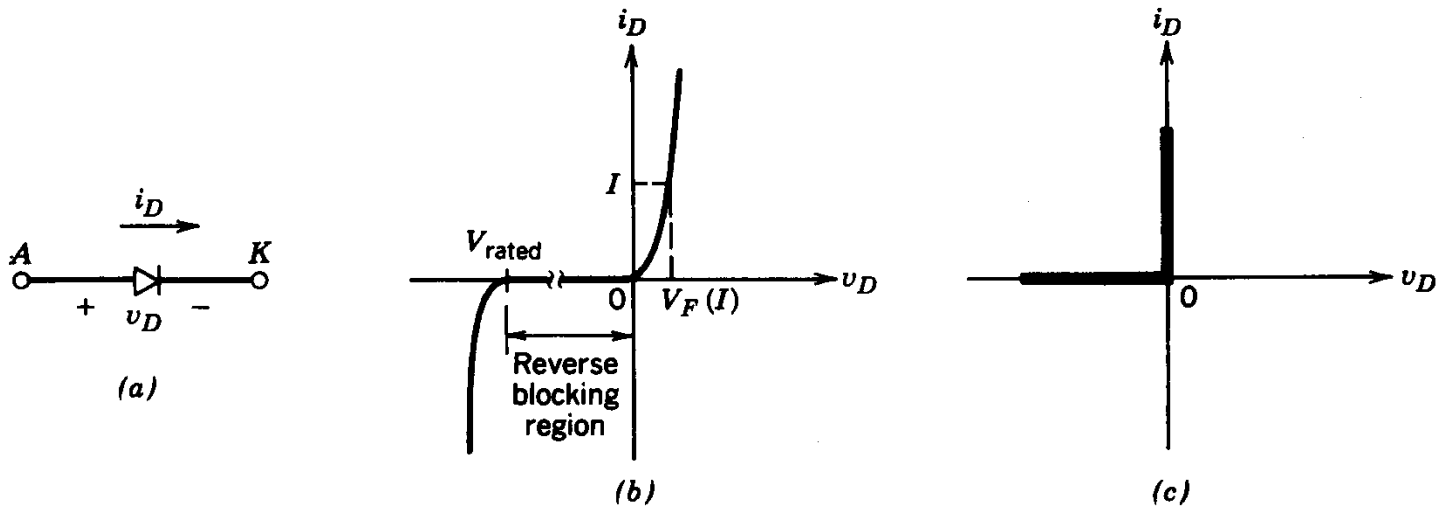
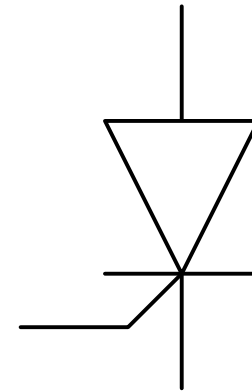
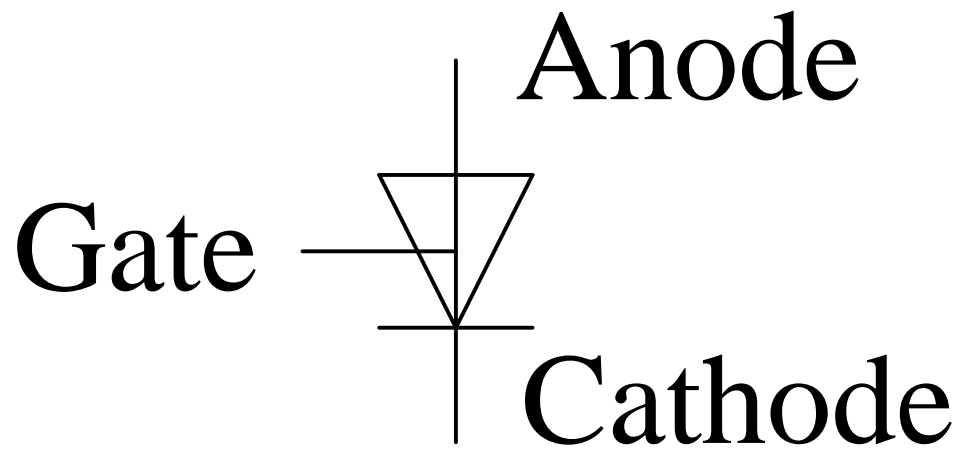


Figure 2-1 Diode: (a) symbol, (b) i - v characteristic, (c) idealized characteristic.

- On and off states controlled by the power circuit

Thyristor



Generic Switch Symbol

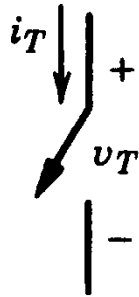


Figure 2-5 Generic controllable switch.

- Idealized switch symbol
- When on, current can flow only in the direction of the arrow
- Instantaneous switching from one state to the other
- Zero voltage drop in on-state
- Infinite voltage and current handling capabilities

Switching Characteristics (linearized)

Switching Power Loss is proportional to:

- switching frequency
- turn-on and turn-off times

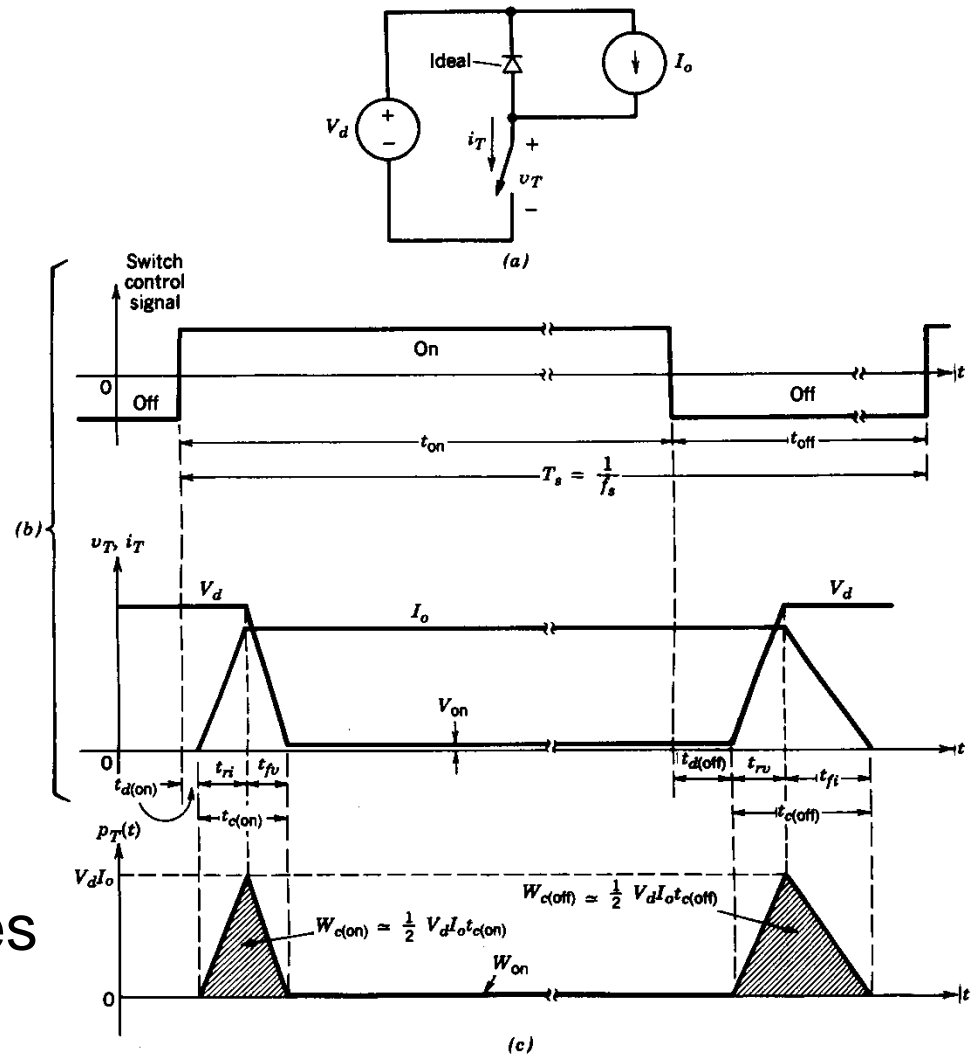


Figure 2-6 Generic-switch switching characteristics (linearized): (a) simplified clamped-inductive-switching circuit, (b) switch waveforms, (c) instantaneous switch power loss.

Switching speed

- Why do we want to switch fast?

Low switching losses

Well defined voltage waveform

- Why do we want to switch slowly?

Voltage sharing

EMI

Electric stress on insulation systems

MOSFETs

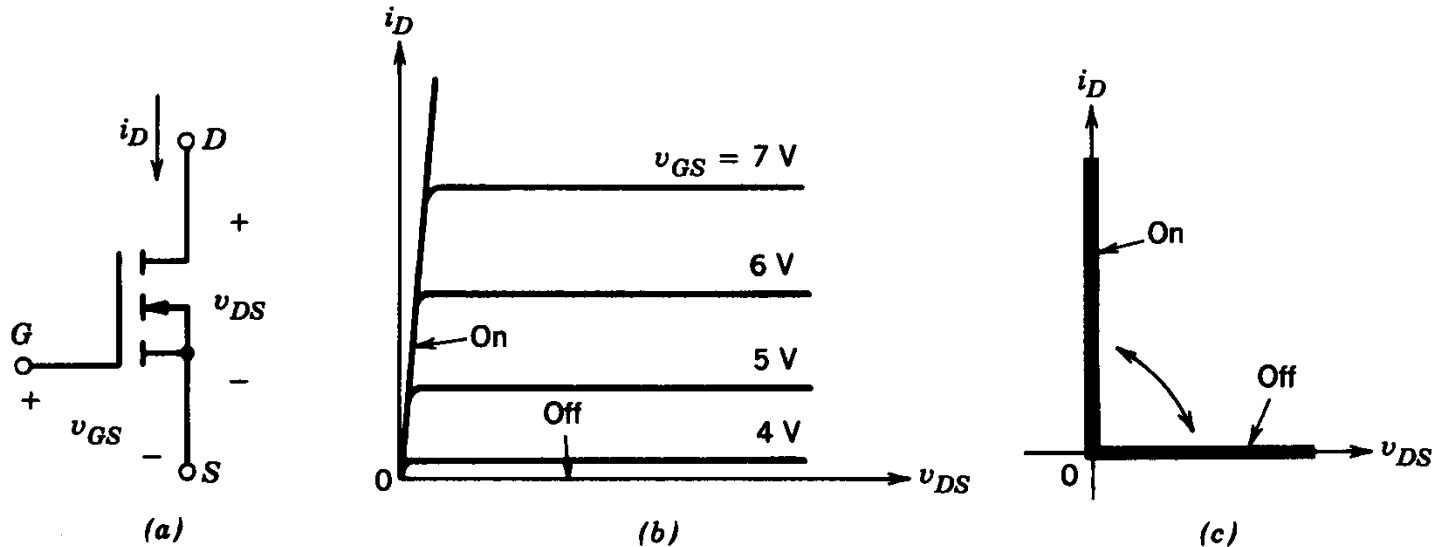


Figure 2-9 *N*-channel MOSFET: (a) symbol, (b) i - v characteristics, (c) idealized characteristics.

- Easy to control by the gate
- Optimal for low-voltage operation at high switching frequencies
- On-state resistance a concern at higher voltage ratings

IGBT

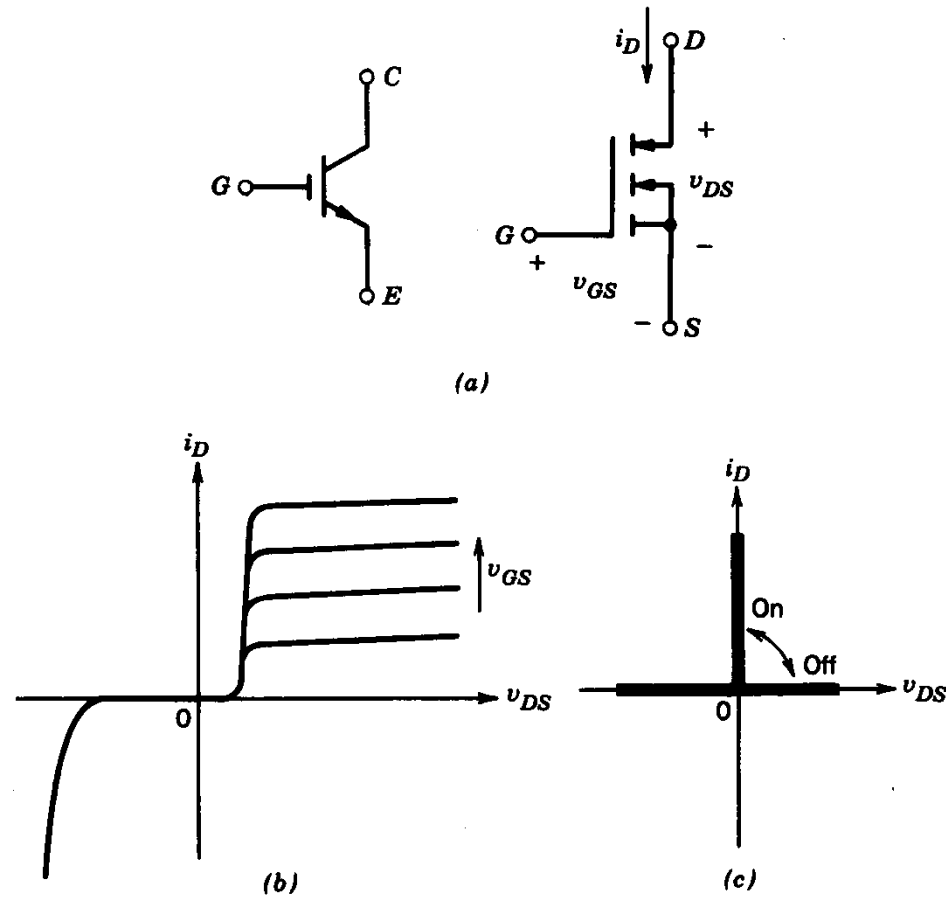


Figure 2-12 An IGBT: (a) symbol, (b) i - v characteristics, (c) idealized characteristics.

IGBT module



IGBT Datasheet

Characteristics		$T_c = 25\text{ }^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 16\text{ mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = V_{CES}$	$T_j = 25\text{ }^\circ\text{C}$	0,2	0,6	mA
		$T_j = 125\text{ }^\circ\text{C}$			mA
V_{CE0}		$T_j = 25\text{ }^\circ\text{C}$	1	1,2	V
		$T_j = 125\text{ }^\circ\text{C}$	0,9	1,1	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25\text{ }^\circ\text{C}$	1,8	2,4	m Ω
		$T_j = 125\text{ }^\circ\text{C}$	2,8	3,4	m Ω
$V_{CE(sat)}$	$I_{Cnom} = 400\text{ A}$, $V_{GE} = 15\text{ V}$	$T_j = 25\text{ }^\circ\text{C}_{chiplev.}$	1,7	2,15	V
		$T_j = 125\text{ }^\circ\text{C}_{chiplev.}$	2	2,45	V
C_{ies}	$V_{CE} = 25$, $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	32		nF
C_{oes}			11		nF
C_{res}			2,2		nF
Q_G	$V_{GE} = -8\text{ V} - +20\text{ V}$		3600		nC
R_{Gint}	$T_j = \text{ }^\circ\text{C}$		1,88		Ω
$t_{d(on)}$	$R_{Gon} = 2\text{ }^\circ\Omega$	$V_{CC} = 600\text{ V}$ $I_C = 400\text{ A}$	290		ns
t_r			60		ns
E_{on}			39		mJ
$t_{d(off)}$	$R_{Goff} = 2\text{ }^\circ\Omega$	$T_j = 125\text{ }^\circ\text{C}$ $V_{GE} = \pm 15\text{ V}$	670		ns
t_f			80		ns
E_{off}			64		mJ
$R_{th(j-c)}$	per IGBT			0,055	K/W

Bond wire lift-off

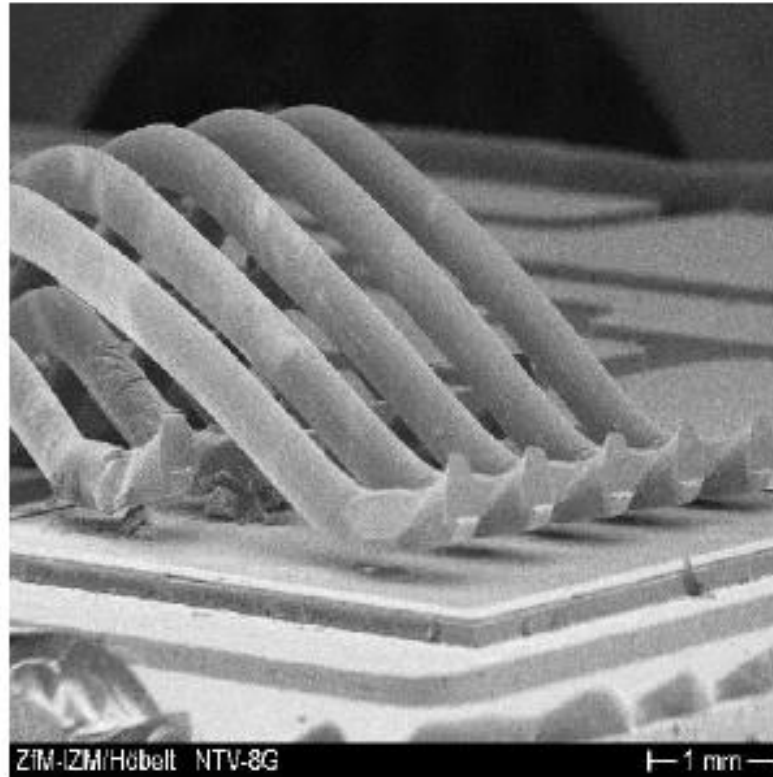


Fig .5: Bond wire lift-off of one-sided LT joined diode after 32000 power cycles

Soldering delamination

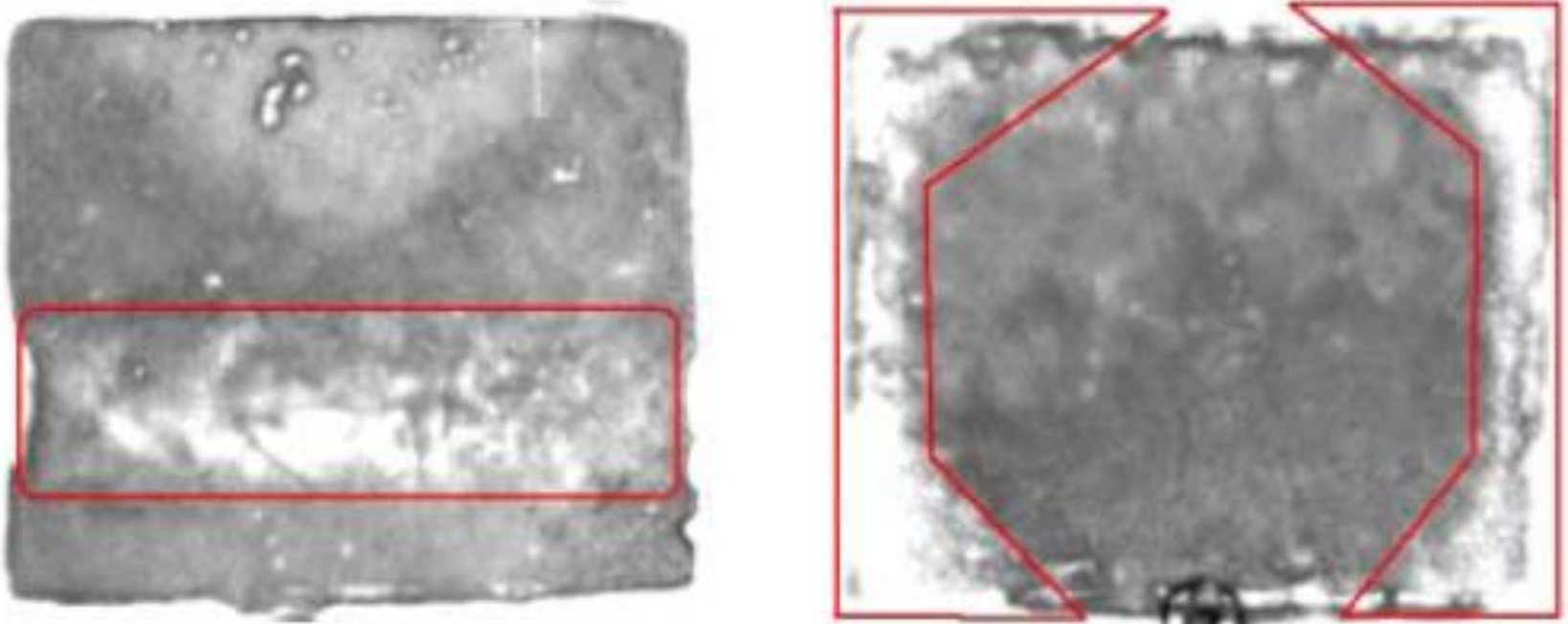


Figure 7: damage below active chips in a lead-free substrate solder joint after power cycling (left) and substrate soldering after 30 000 passive thermal cycles (right) in modules with AlSiC base plate.

V_{CE}	=	2500 V	ABB StakPak™ H Series
I_C	=	2000 A	
			5SNR 20H2501
PRELIMINARY			

Doc. No. 5SYA1582-03 May 07

- High SOA
- Fails into stable shorted state
- High tolerance to uneven mounting pressure
- Designed for series connection
- Explosion resistant package
- Modular design concept, available for a wide range of current ratings
- SPT chip set



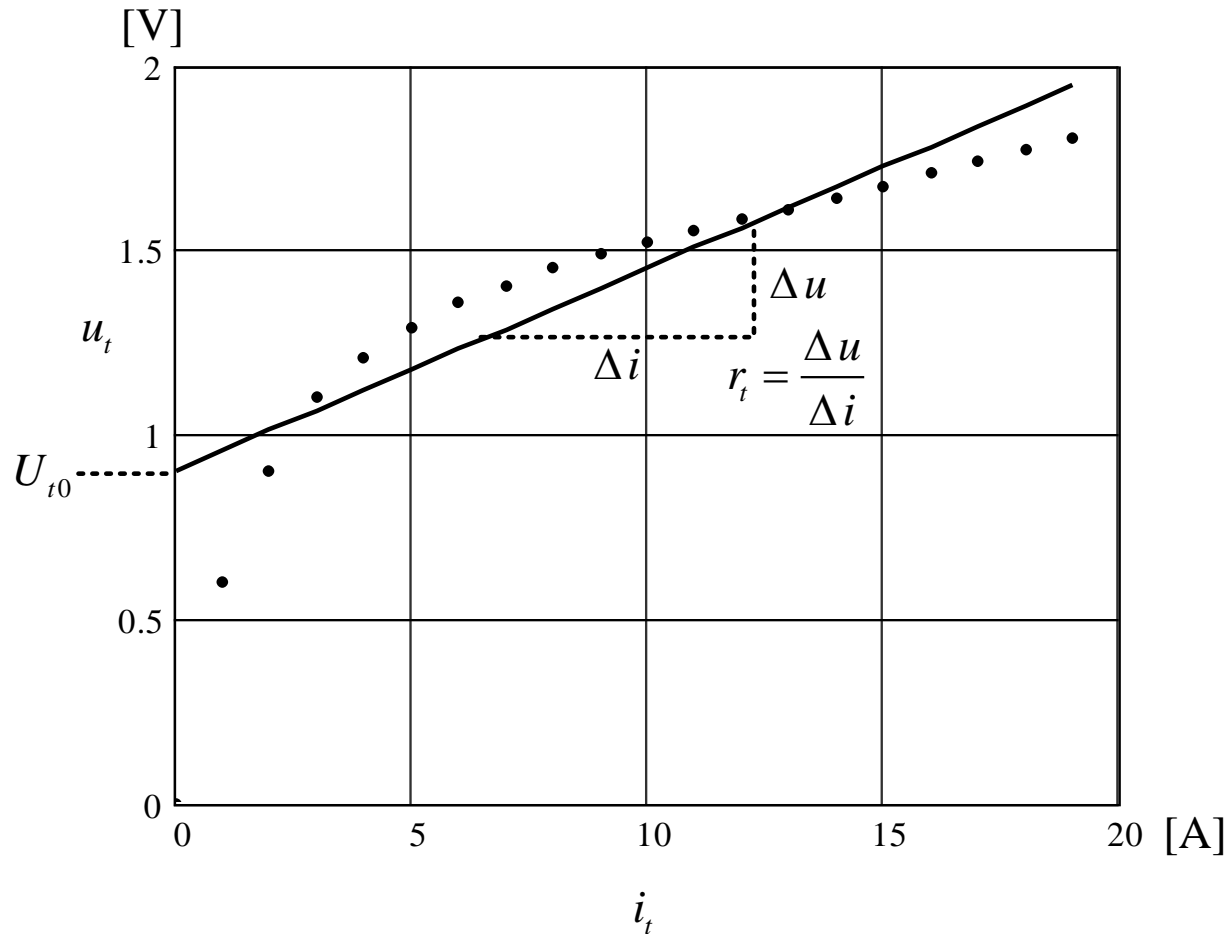
Maximum Rated Values¹⁾

Parameter ²⁾	Symbol	Conditions	min	max	Unit
Collector-emitter voltage	V_{CES}			2500	V
DC collector current	I_C	$T_o = 75\text{ °C}$		2000	A
Repetitive peak collector current	I_{CM}			4000	A
Gate-emitter voltage	V_{GES}			± 20	V
Total power dissipation	P_{tot}	$T_o = 25\text{ °C}$, (IGBT)		18000	W
DC forward current	I_F	$T_o = 75\text{ °C}$		2000	A
Repetitive peak forward current	I_{FM}			4000	A
Surge current	I_{FSM}	$V_R = 0\text{ V}$, $t_p = 10\text{ ms}$, $T_{vj} = 125\text{ °C}$, half-sinewave		23	kA
IGBT short circuit SOA	t_{psc}	$V_{CC} = 1500\text{ V}$, $V_{CEM} \leq 2500\text{ V}$, $V_{GE} \leq 15\text{ V}$		10	μs
Junction temperature	T_{vj}		5	125	°C
Storage temperature	T_{stg}		-40	70	°C
Mounting force ²⁾	F_M		65	95	kN

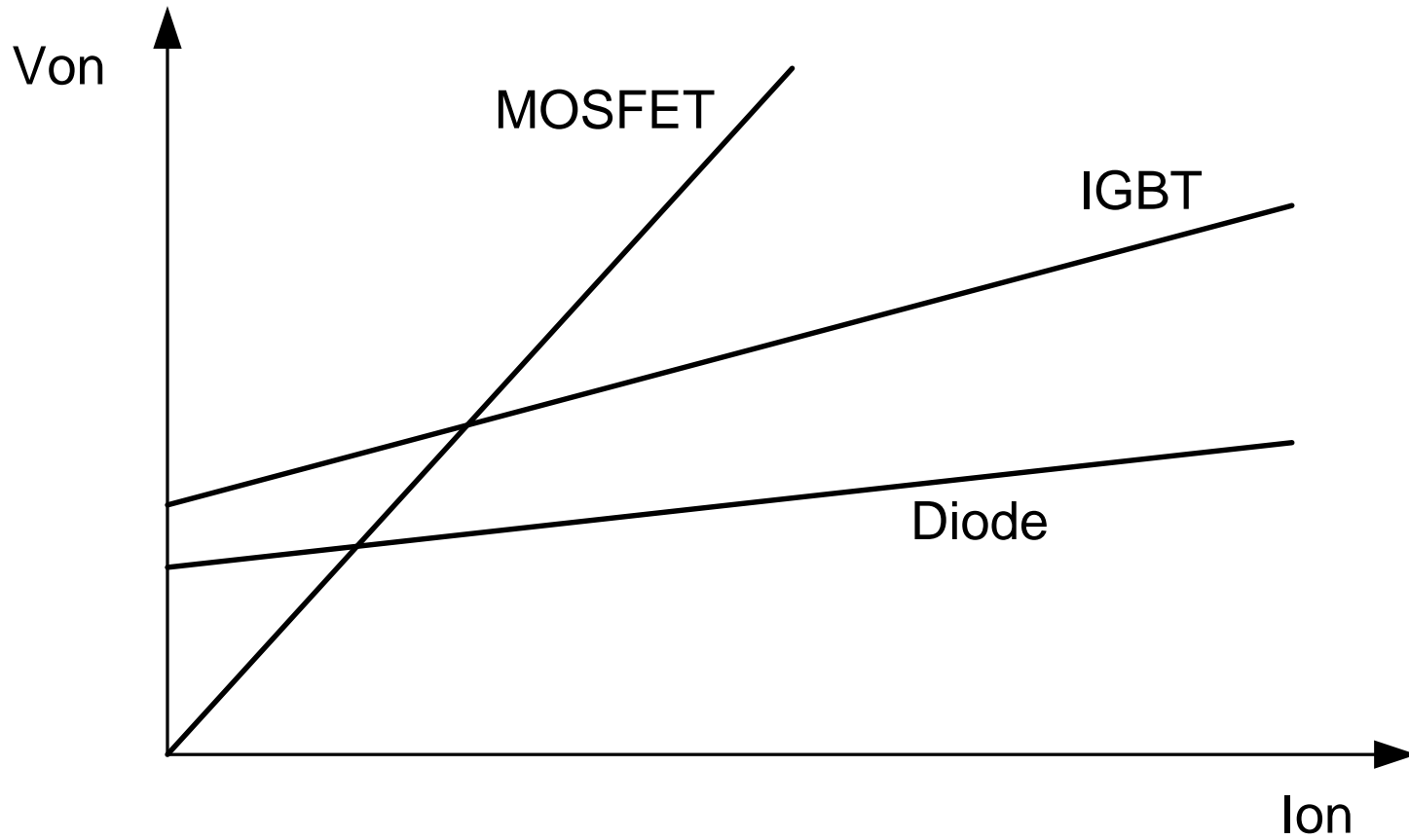
¹⁾Maximum rated values indicate limits beyond which damage to the device may occur per IEC 60747-9

²⁾For detailed mounting instructions refer to ABB document no. 5SYA 2037-02

Approximation of voltage drop



Voltage drop



Review of basics

- Steady state
- Mean value, RMS-value
- Phasor representation
- Active, reactive, and complex power
- Three-phase circuits
- Inductor
- Capacitor

Block Diagram of DC-DC Converters

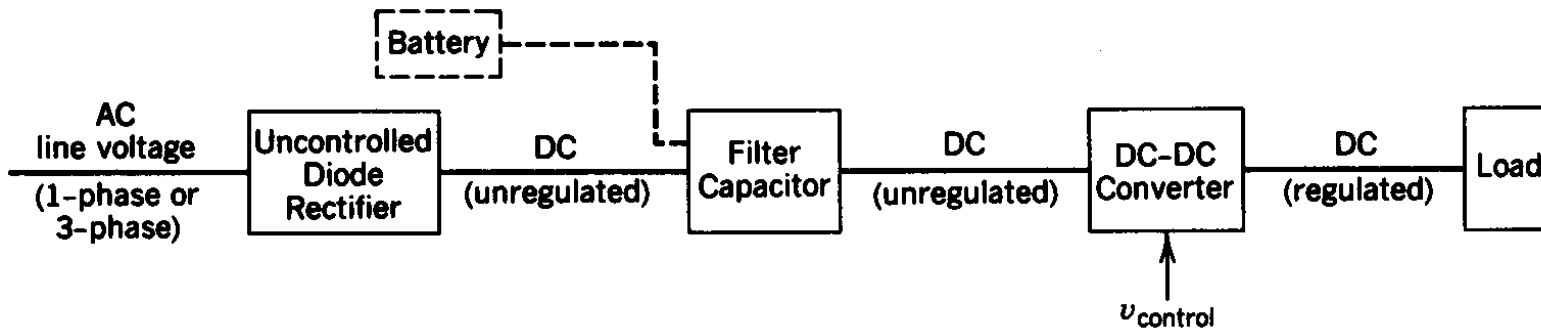
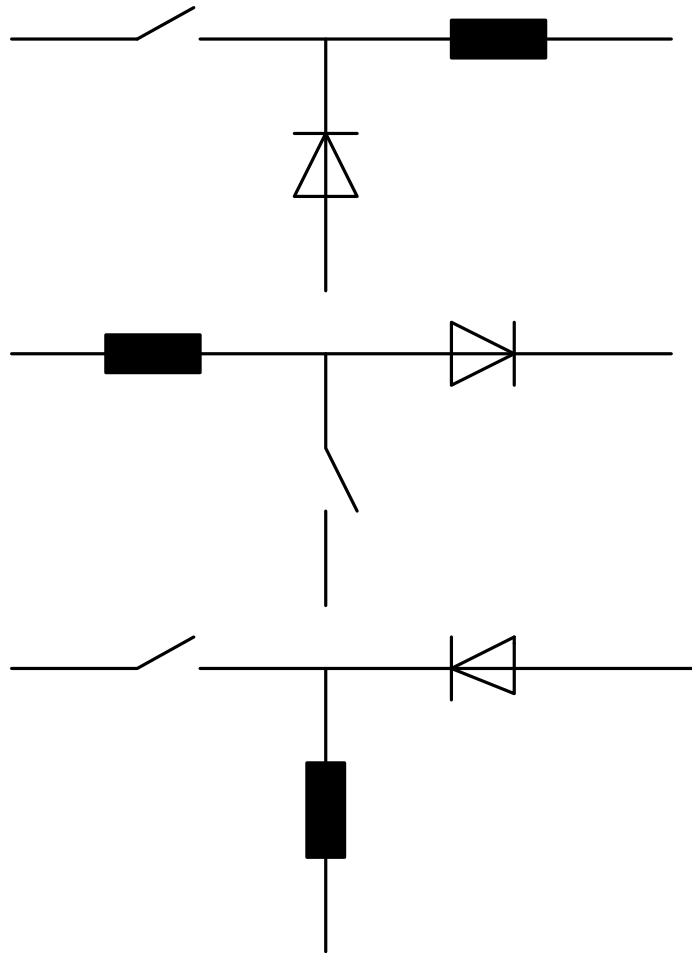


Figure 7-1 A dc-dc converter system.

- Functional block diagram

DC-DC converter types



Stepping Down a DC Voltage

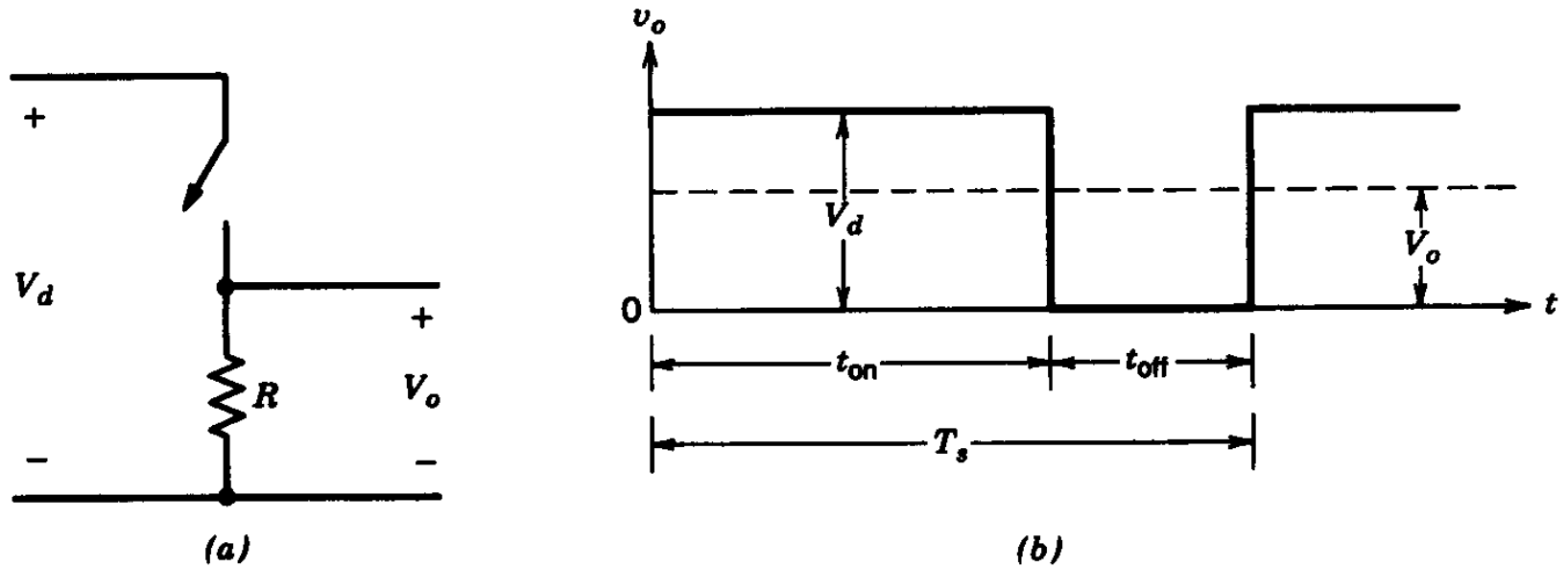
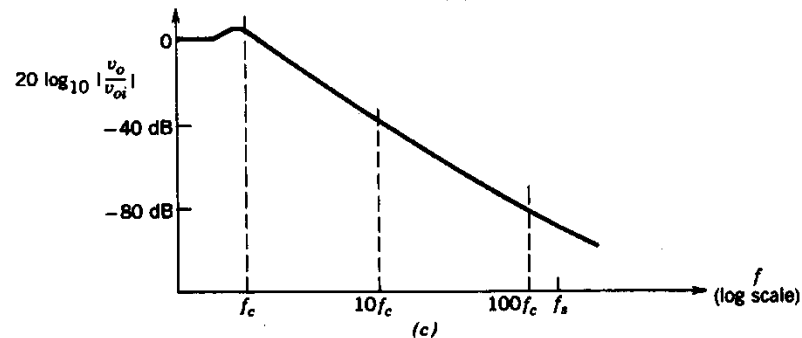
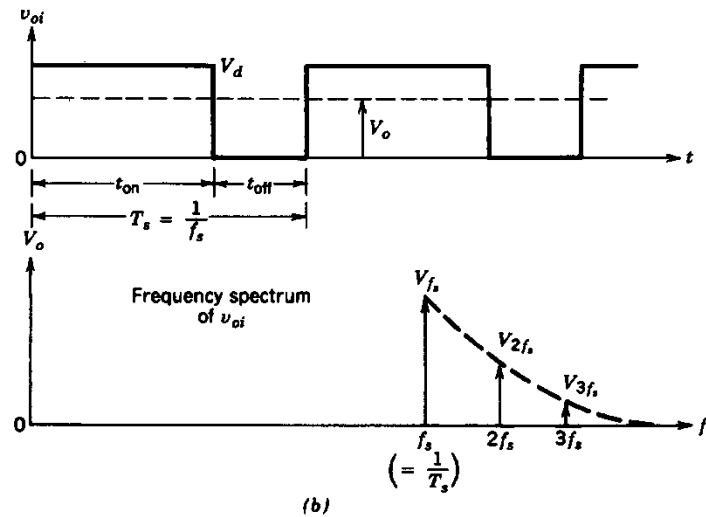
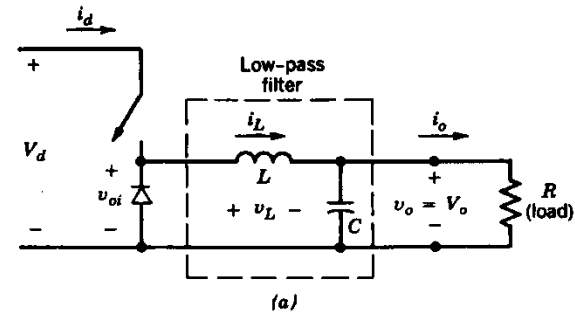


Figure 7-2 Switch-mode dc-dc conversion.

Step-Down DC-DC Converter



- Pulsating input to the low-pass filter

Figure 7-4 Step-down dc-dc converter.

Step-Down DC-DC Converter: Waveforms

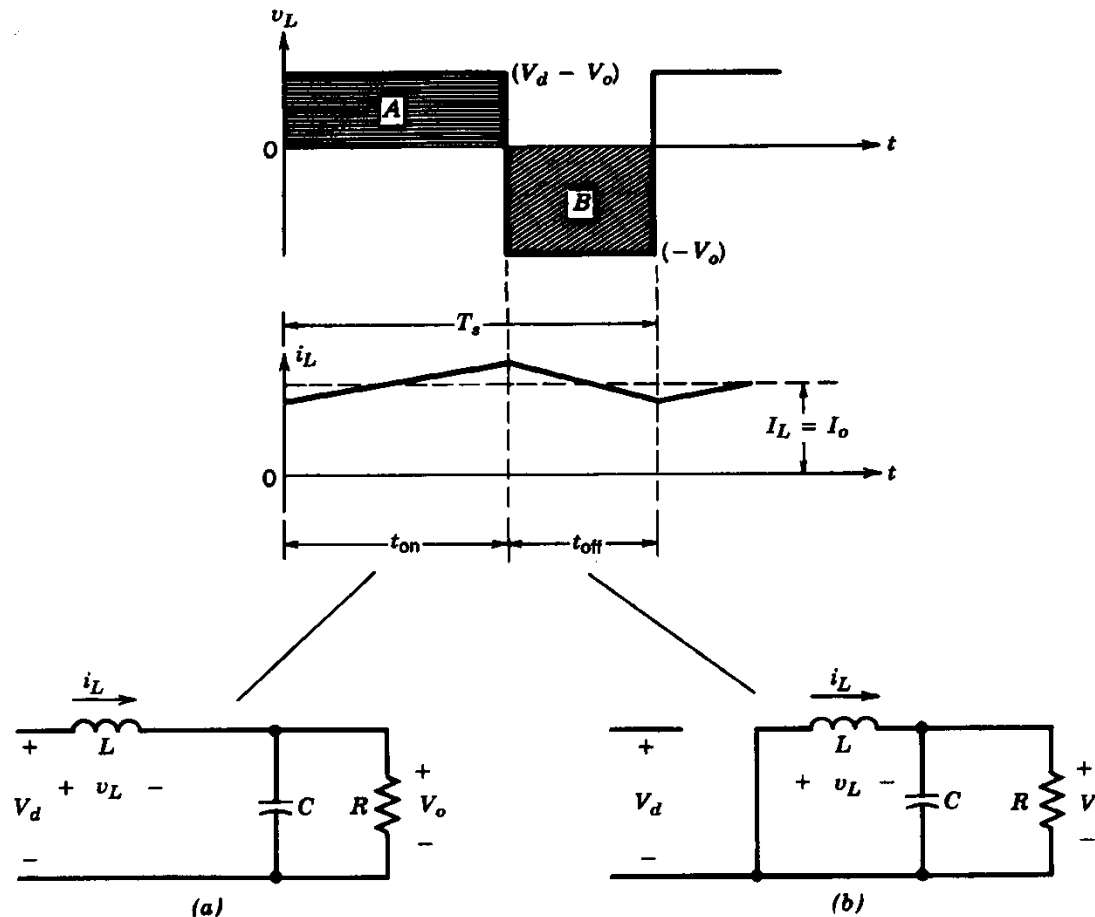


Figure 7-5 Step-down converter circuit states (assuming i_L flows continuously): (a) switch on; (b) switch off.

- Steady state; inductor current flows continuously